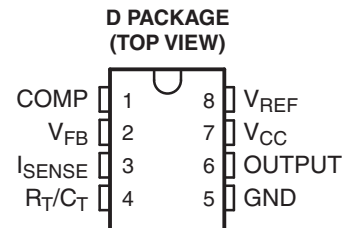


CURRENT-MODE PWM CONTROLLER

FEATURES

- Qualified for Automotive Applications
- Extended Temperature Performance of -40°C to 125°C
- Optimized for Off-Line and DC-to-DC Converters
- Low Start-Up Current ($<0.5\text{ mA}$)
- Trimmed Oscillator-Discharge Current
- Automatic Feed-Forward Compensation
- Pulse-by-Pulse Current Limiting
- Enhanced Load-Response Characteristics
- Under-Voltage Lockout With Hysteresis
- Double-Pulse Suppression
- High-Current Totem-Pole Output
- Internally Trimmed Bandgap Reference
- 500-kHz Operation
- Low R_o Error Amp



DESCRIPTION/ORDERING INFORMATION

The UC2843A control IC is a pin-for-pin compatible improved version of the UC2843. Providing the necessary features to control current mode switched mode power supplies, this device has the following improved features. Start up current is specified to be less than 0.5 mA. Oscillator discharge is trimmed to 8.3 mA. During undervoltage lockout, the output stage can sink at least 10 mA at less than 1.2 V for V_{CC} over 5 V.

PART NUMBER	UVLO ON	UVLO OFF	MAXIMUM DUTY CYCLE
UC2843A	8.5 V	7.9 V	<100%

ORDERING INFORMATION⁽¹⁾

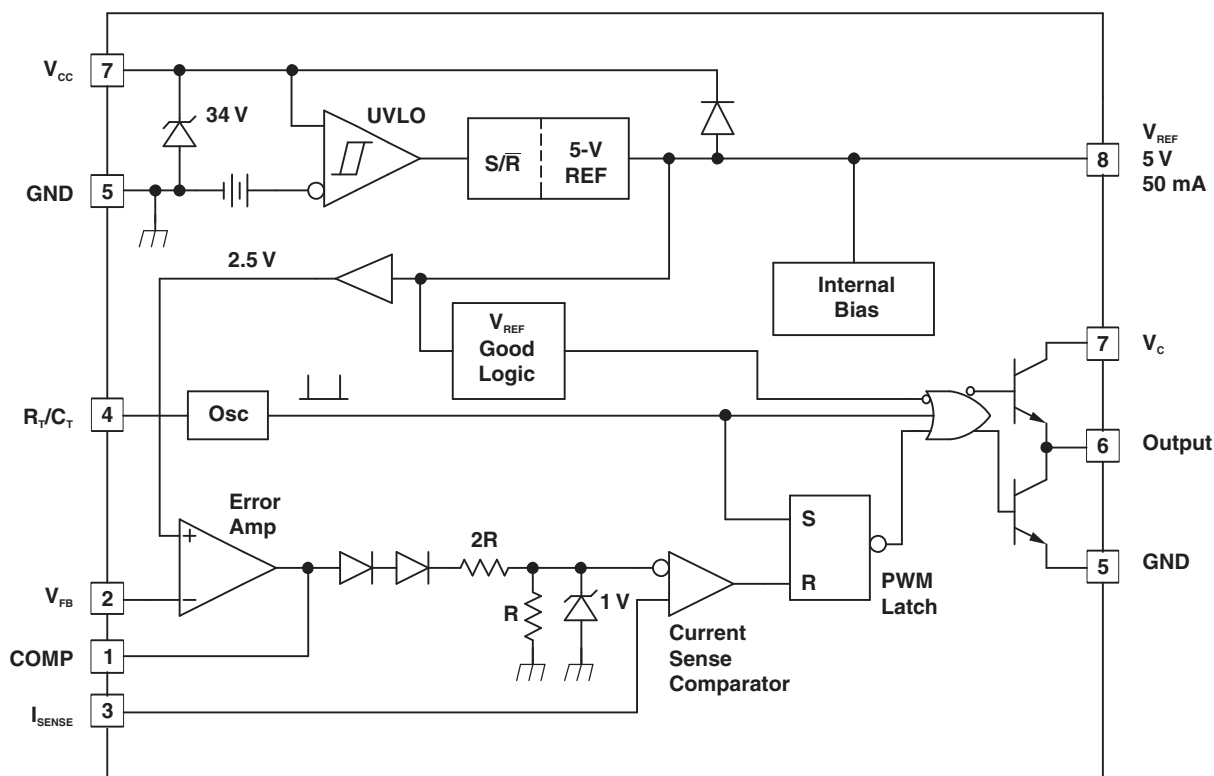
T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC-8 – D8	Reel of 2500	UC2843AQD8RQ1	UC2843AQ

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FUNCTIONAL BLOCK DIAGRAM

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

over operating free-air temperature range (unless otherwise noted)

	VALUE	UNIT
V_{CC} voltage (low impedance source)	30	V
V_{CC} voltage (I_{CC} mA)	Self limiting	
I_O Output current	± 1	A
Output energy (capacitive load)	5	μ J
Analog inputs (pins 3 and 5)	-0.3 to 6.3	V
Error amplifier output sink current	10	mA
Power dissipation at $T_A < 25^\circ\text{C}$ (14-pin D package)	1	W
θ_{JA} Package thermal impedance ⁽³⁾	97	$^\circ\text{C}/\text{W}$
T_{stg} Storage temperature range	-65 to 150	$^\circ\text{C}$
Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds	260	$^\circ\text{C}$

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Unless otherwise indicated, voltages are reference to ground, and currents are positive into and negative out of the specified terminals.
- (3) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

ELECTRICAL CHARACTERISTICS

 $T_A = -40^{\circ}\text{C}$ to 125°C , $V_{CC} = 15\text{ V}^{(1)}$, $R_T = 10\text{ k}\Omega$, $C_T = 3.3\text{ nF}$, $T_A = T_J$ (unless otherwise stated)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Reference Section						
Output voltage	$T_J = 25^{\circ}\text{C}$, $I_O = 1\text{ mA}$	4.95	5.0	5.05	V	
Line regulation voltage	$V_{IN} = 12\text{ V}$ to 25 V		6	20	mV	
Load regulation voltage	$I_O = 1\text{ mA}$ to 20 mA		6	25	mV	
Temperature stability ⁽²⁾⁽³⁾			0.2	0.4	mV/ $^{\circ}\text{C}$	
Total output variation voltage	Line, load, temperature	4.9		5.1	V	
Output noise voltage	$f = 10\text{ Hz}$ to 10 kHz		50		μV	
Long term stability	1000 hours		5	25	mV	
Output short-circuit current		-30	-100	-180	mA	
Oscillator Section						
Initial accuracy ⁽⁴⁾	$T_J = 25^{\circ}\text{C}$	47	52	57	kHz	
Voltage stability	$V_{CC} = 12\text{ V}$ to 25 V		0.2	1	%	
Temperature stability	$T_A = \text{MIN}$ to MAX		5		%	
Amplitude peak-to-peak	V pin 7		1.7		V	
Discharge current ⁽⁵⁾	V pin 7 = 2 V	$T_J = 25^{\circ}\text{C}$	7.8	8.3	8.8	mA
		$T_J = \text{Full range}$	7.5		8.8	
Error Amplifier Section						
Input voltage	COMP = 2.5 V	2.45	2.5	2.55	V	
Input bias current			-0.3	-1	μA	
Open loop voltage gain (AVOL)	$V_O = 2\text{ V}$ to 4 V	65	90		dB	
Unity gain bandwidth ⁽³⁾	$T_J = 25^{\circ}\text{C}$	0.7	1		MHz	
PSRR	$V_{CC} = 12\text{ V}$ to 25 V	60	70		dB	
Output sink current	FB = 2.7 V , COMP = 1.1 V	2	6		mA	
Output source current	FB = 2.3 V , COMP = 5 V	-0.5	-0.8		mA	
VOUT high	FB = 2.3 V , $R_L = 15\text{ k}\Omega$ to GND	5	6		V	
VOUT low	FB = 2.7 V , $R_L = 15\text{ k}\Omega$ to V_{REF}		0.7	1.1	V	
Current Sense Section						
Gain ⁽⁶⁾⁽⁷⁾		2.85	3	3.15	V/V	
Maximum input signal ⁽⁶⁾	COMP = 5 V	0.9	1	1.1	V	
PSRR ⁽⁶⁾	$V_{CC} = 12\text{ V}$ to 25 V		70		dB	
Input bias current			-2	-10	μA	
Delay to output ⁽³⁾	$I_{SENSE} = 0\text{ V}$ to 2 V		150	300	ns	

(1) Adjust V_{CC} above the start threshold before setting at 15 V .

(2) Temperature stability, sometimes referred to as average temperature coefficient, is described by the equation:

Temperature Stability = $(V_{REF}(\text{max}) - V_{REF}(\text{min})) / (T_J(\text{max}) - T_J(\text{min}))$. $V_{REF}(\text{max})$ and $V_{REF}(\text{min})$ are the maximum and minimum reference voltage measured over the appropriate temperature range. Note that the extremes in voltage do not necessarily occur at the extremes in temperature.

(3) Specified by design.

(4) Output frequency equals oscillator frequency for the UC2843A.

(5) This parameter is measured with $R_T = 10\text{ k}\Omega$ to V_{REF} . This contributes approximately $300\text{ }\mu\text{A}$ of current to the measurement. The total current flowing into the R_T/R_C pin is approximately $300\text{ }\mu\text{A}$ higher than the measured value.

(6) Parameter measured at trip point of latch with V_{FB} at 0 V .

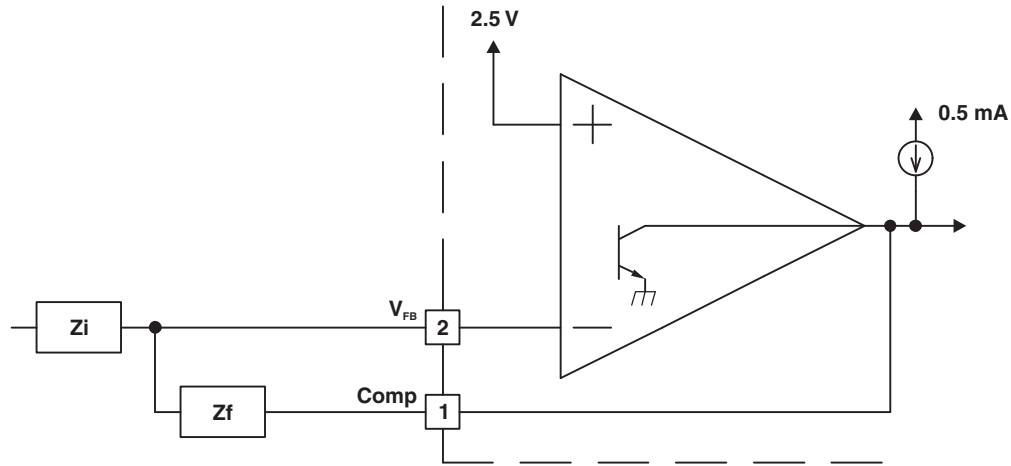
(7) Gain is defined by: $A = \Delta V_{COMP} / \Delta V_{SENSE}$; $0 \leq V_{SENSE} \leq 0.8\text{ V}$.

ELECTRICAL CHARACTERISTICS (continued)
 $T_A = -40^{\circ}\text{C}$ to 125°C , $V_{CC} = 15\text{ V}$, $R_T = 10\text{ k}\Omega$, $C_T = 3.3\text{ nF}$, $T_A = T_J$ (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Output Section (OUT)						
Low level output voltage	$I_{OUT} = 20\text{ mA}$			0.1	0.4	V
	$I_{OUT} = 200\text{ mA}$			15	2.2	
High level output voltage	$I_{OUT} = -20\text{ mA}$		13	13.5		V
	$I_{OUT} = -200\text{ mA}$		12	13.5		
Rise time ⁽⁸⁾	$C_L = 1\text{ nF}$	$T_J = 25^{\circ}\text{C}$		50	150	ns
Fall time ⁽⁸⁾	$C_L = 1\text{ nF}$	$T_J = 25^{\circ}\text{C}$		50	150	ns
UVLO saturation	$V_{CC} = 5\text{ V}$, $I_{OUT} = 10\text{ mA}$			0.7	1.2	V
Undervoltage Lockout Section (UVLO)						
Start threshold			7.8	8.4	9	V
Minimum operation voltage after turn on			7	7.6	8.2	V
PWM Section						
Maximum duty cycle			94	96	100	%
Minimum duty cycle					0	%
Total Standby Current						
Start-up current				0.3	0.5	mA
Operating supply current	$FB = 0\text{ V}$, $SENSE = 0\text{ V}$			11	17	mA
V_{CC} internal zener voltage	$I_{CC} = 25\text{ mA}$		30	34		V

(8) Specified by design.

PARAMETER MEASUREMENT INFORMATION



A. The error amplifier can source up to 0.5 mA and sink up to 2 mA.

Figure 1. Error Amp Configuration

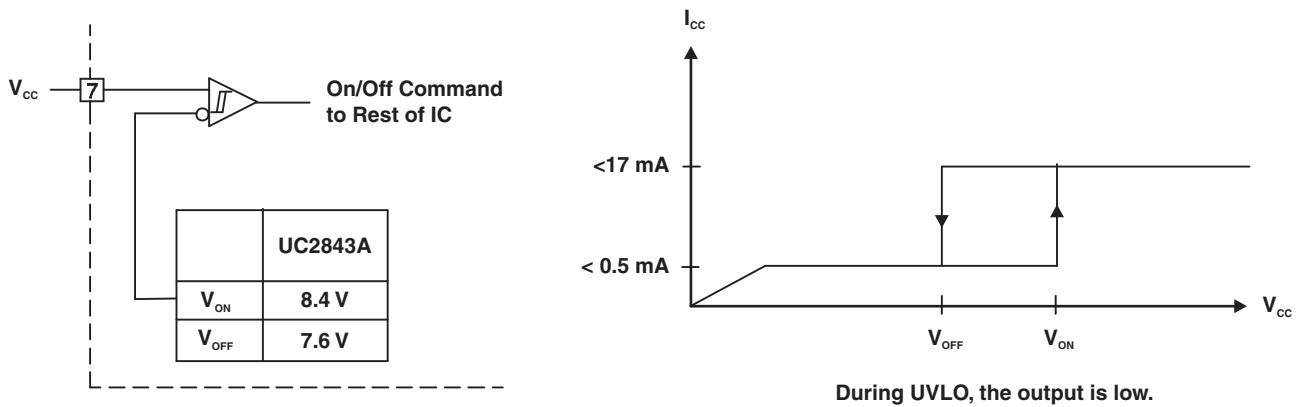
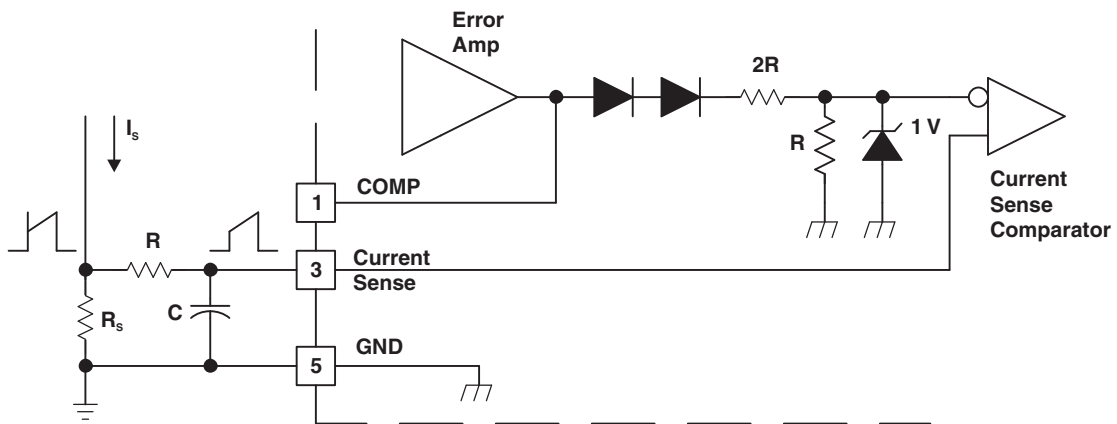


Figure 2. Undervoltage Lockout



A. Peak current (I_s) is determined by the formula: $I_{smax} = 1.0 V/R_s$
 A small RC filter may be required to suppress switch transients.

Figure 3. Current Sense Circuit

PARAMETER MEASUREMENT INFORMATION (continued)

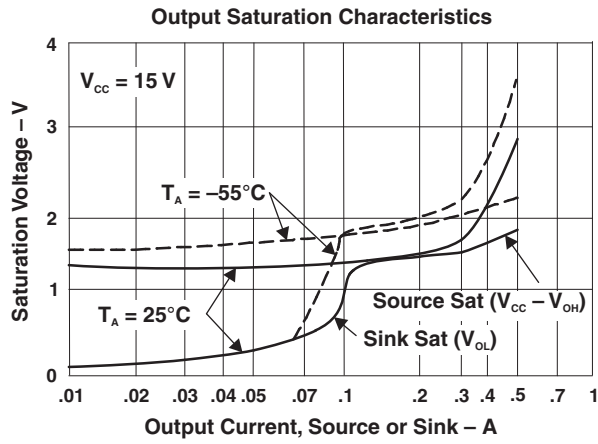


Figure 4.

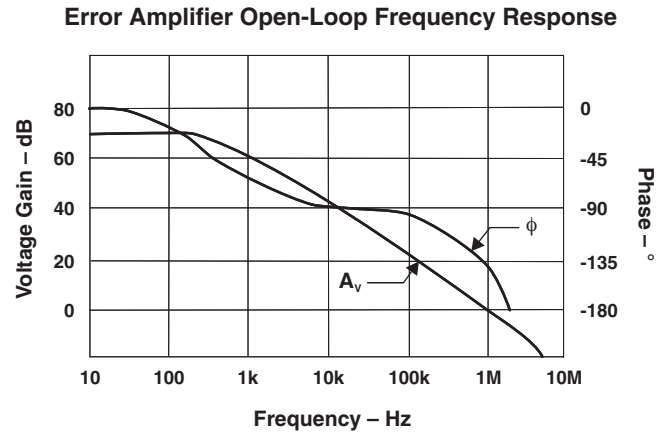


Figure 5.

APPLICATION INFORMATION

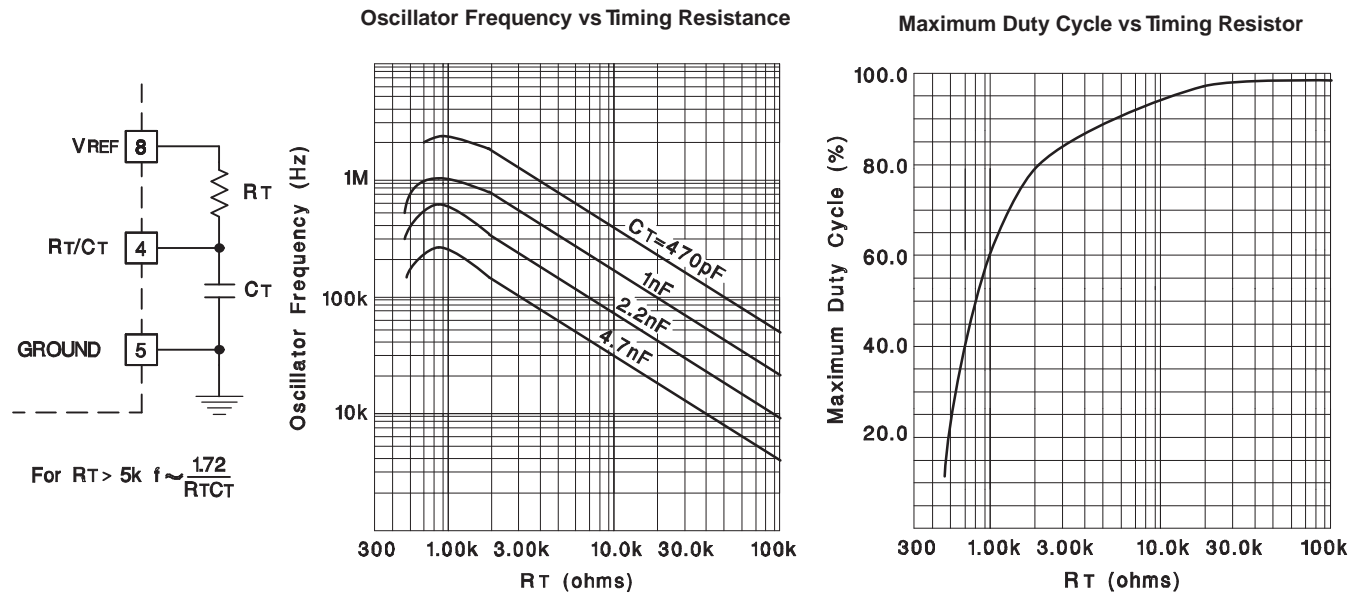
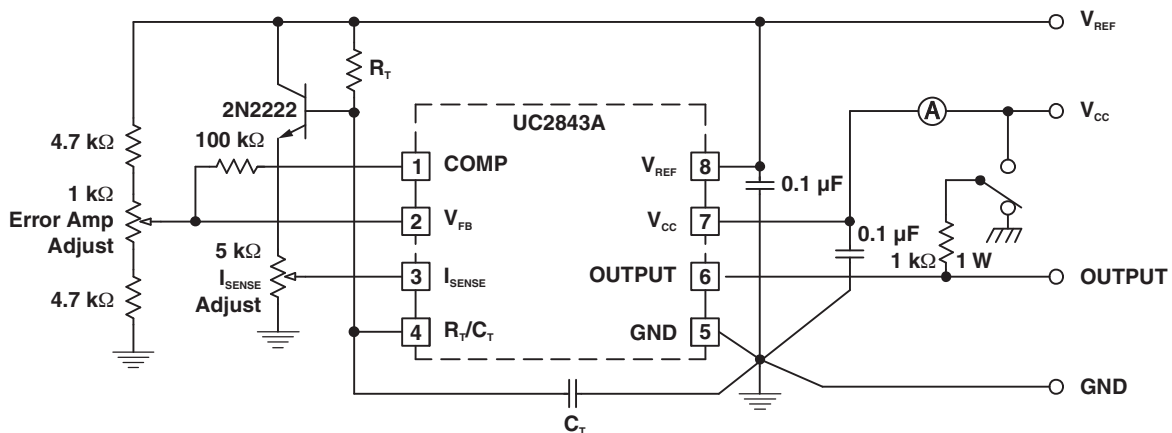


Figure 6. Oscillator



- A. High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

Figure 7. Open-Loop Laboratory Text Fixture

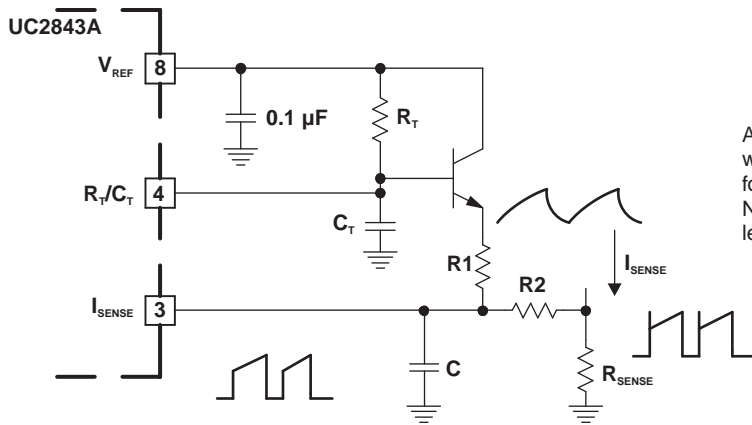
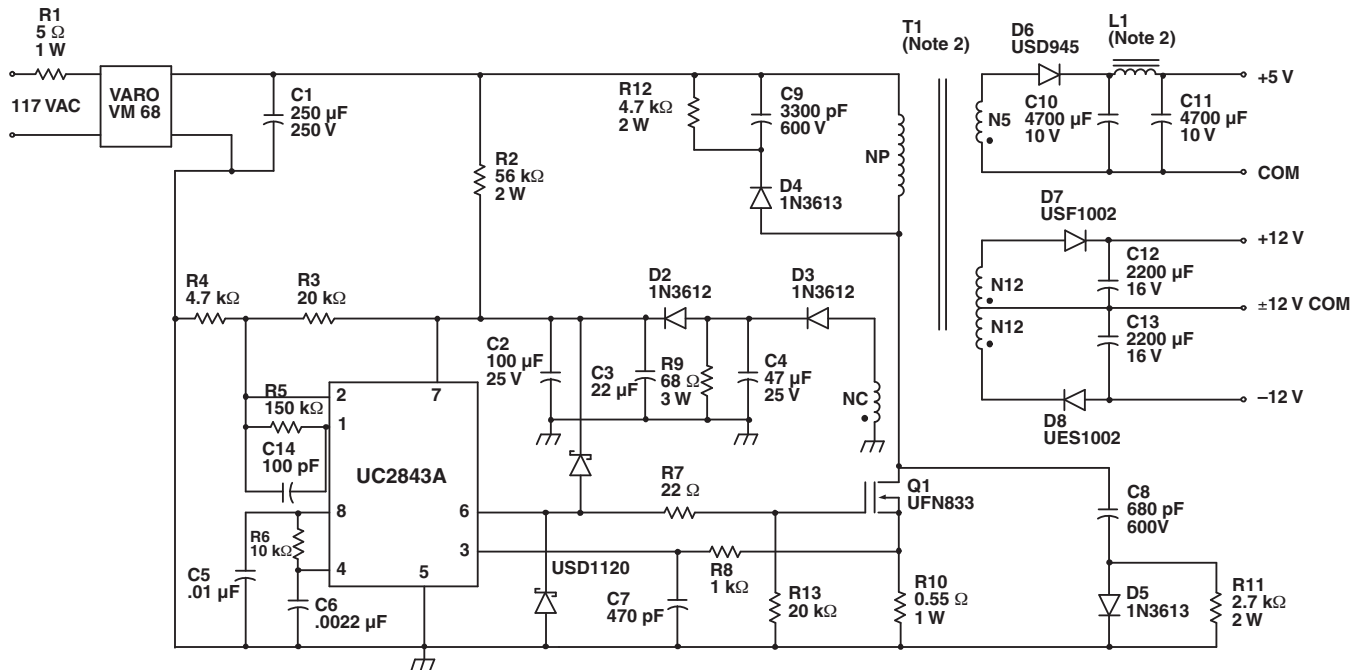


Figure 8. Slope Compression





Power Supply Specifications

1. Input Voltage 95 VAC to 130 VAC (50 Hz/60 Hz)
2. Line Isolation 3750 V
3. Switching Frequency 40 kHz
4. Efficiency, Full Load 70%
5. Output Voltage:
 - A. 5 V \pm 5%; 1-A to 4-A Load
 - B. 12 V \pm 3%; 0.1-A to 0.3-A Load; Ripple voltage: 100 mV P-P Max
 - C. -12 V \pm 3%; 0.1-A to 0.3-A Load; Ripple voltage: 100 mV P-P Max

Figure 9. Off-Line Flyback Regulator

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UC2843AQD8RG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2843AQ ~ UC2843AQ)	
UC2843AQD8RQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2843AQ ~ UC2843AQ)	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF UC2843A-Q1 :

- Catalog: [UC2843A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2843AQD8RQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2843AQD8RQ1	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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